

## STD20NF06

# N-CHANNEL 60V - 0.032 Ω - 24A DPAK STripFET™ II POWER MOSFET

#### PRELIMINARY DATA

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STD20NF06	60 V	< 0.040 Ω	24 A

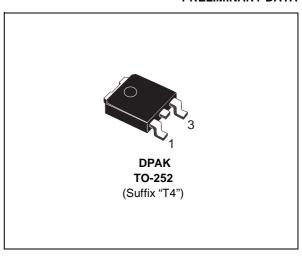
- TYPICAL  $R_{DS}(on) = 0.032 \Omega$
- EXCEPTIONAL dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- APPLICATION ORIENTED CHARACTERIZATION
- SURFACE-MOUNTING DPAK (TO-252) POWER PACKAGE IN TAPE & REEL (SUFFIX "T4")

#### **DESCRIPTION**

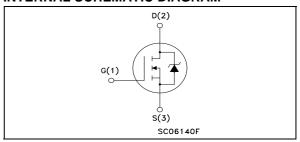
This Power MOSFET is the latest development of STMicroelectronis unique "Single Feature Size<sup>TM"</sup> strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

#### **APPLICATIONS**

- AUDIO AMPLIFIERS
- POWER TOOLS
- AUTOMOTIVE ENVIRONMENT



#### **INTERNAL SCHEMATIC DIAGRAM**



#### **Ordering Information**

SALES TYPE	MARKING	PACKAGE	PACKAGING
STD20NF06	STD20NF06	TO-252	TAPE & REEL

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	60	V
$V_{DGR}$	Drain-gate Voltage ( $R_{GS} = 20 \text{ k}\Omega$ )	60	V
V <sub>GS</sub>	Gate- source Voltage	± 20	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 25°C	24	Α
ΙD	Drain Current (continuous) at T <sub>C</sub> = 100°C	17	Α
I <sub>DM</sub> (●)	Drain Current (pulsed)	96	Α
P <sub>tot</sub>	Total Dissipation at T <sub>C</sub> = 25°C	60	W
	Derating Factor	0.4	W/°C
dv/dt <sup>(1)</sup>	Peak Diode Recovery voltage slope	10	V/ns
E <sub>AS</sub> (2)	Single Pulse Avalanche Energy	300	mJ
T <sub>stg</sub>	Storage Temperature	-55 to 175	°C
Tj	Operating Junction Temperature	-55 to 175	

<sup>(•)</sup> Pulse width limited by safe operating area.

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<sup>(1)</sup> IsD  $\leq$ 24A, di/dt  $\leq$ 100A/µs, VDD  $\leq$  V(BR)DSS, Tj  $\leq$  TJMAX (2) Starting Tj = 25 °C, ID =10 A, VDD = 45V

#### THERMAL DATA

Rthj-case Rthj-amb T <sub>I</sub>	Thermal Resistance Junction-case Thermal Resistance Junction-ambient Maximum Lead Temperature For Soldering Purpose (1.6 mm from case, for 10 sec)	Max Max	2.5 100 275	°C/W °C/W
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# **ELECTRICAL CHARACTERISTICS** ( $T_{CASE} = 25~^{\circ}C$ UNLESS OTHERWISE SPECIFIED) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)</sub> DSS	Drain-source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0$	60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	$V_{DS} = Max Rating$ $V_{DS} = Max Rating T_C = 125$ °C			1 10	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 20V			±100	nA

#### ON (\*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$	$I_D = 250 \mu A$	2		4	V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 12 A		0.032	0.040	Ω

#### **DYNAMIC**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
gfs (*)	Forward Transconductance	$V_{DS} = 25 \text{ V}$ $I_{D} = 12 \text{ A}$		15		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25V f = 1 MHz V_{GS} = 0$		690 170 68		pF pF pF

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#### **ELECTRICAL CHARACTERISTICS** (continued)

#### **SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on Delay Time Rise Time	$\begin{array}{ccc} V_{DD} = 30 \text{ V} & I_D = 10 \text{ A} \\ R_G = 4.7 \; \Omega & V_{GS} = 10 \text{ V} \\ \text{(Resistive Load, Figure 3)} \end{array}$		10 30		ns ns
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V <sub>DD</sub> = 48 V I <sub>D</sub> = 20 A V <sub>GS</sub> = 10 V		23 5 7.5	31	nC nC nC

#### **SWITCHING OFF**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(off)</sub> t <sub>f</sub>	Turn-off Delay Time Fall Time	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$		30 8		ns ns

#### **SOURCE DRAIN DIODE**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> (•)	Source-drain Current Source-drain Current (pulsed)				24 96	A A
V <sub>SD</sub> (*)	Forward On Voltage	I <sub>SD</sub> = 96 A V <sub>GS</sub> = 0			1.5	V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 96 \text{ A}$ di/dt = $100 \text{A}/\mu \text{s}$ $V_{DD} = 20 \text{ V}$ $T_j = 150 ^{\circ} \text{C}$ (see test circuit, Figure 5)		65 150 4.6		ns nC A

<sup>(\*)</sup>Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %. (•)Pulse width limited by safe operating area.

Fig. 1: Unclamped Inductive Load Test Circuit

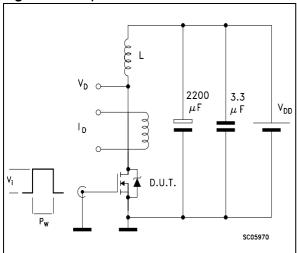
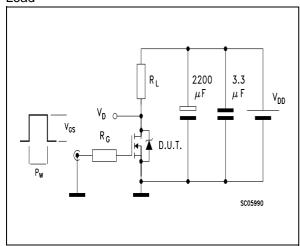


Fig. 3: Switching Times Test Circuits For Resistive Load



**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times

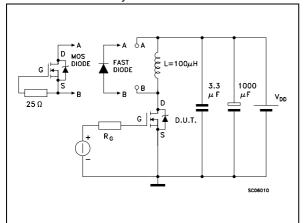


Fig. 2: Unclamped Inductive Waveform

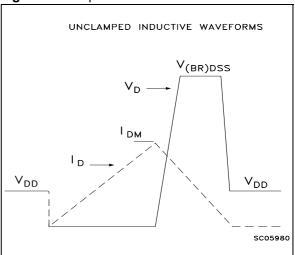
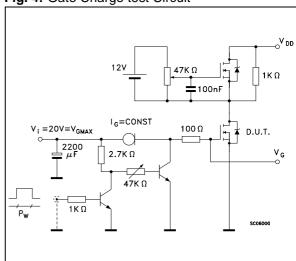


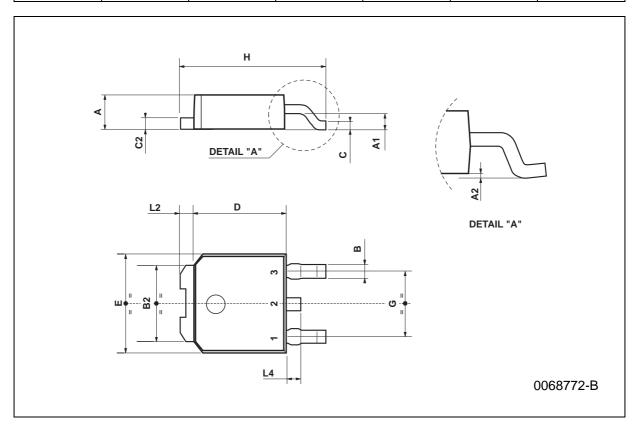
Fig. 4: Gate Charge test Circuit



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## **TO-252 (DPAK) MECHANICAL DATA**

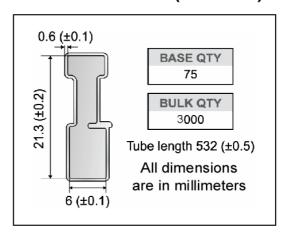
DIM.		mm		inch		
Din.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A2	0.03		0.23	0.001		0.009
В	0.64		0.9	0.025		0.035
B2	5.2		5.4	0.204		0.212
С	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
Е	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
Н	9.35		10.1	0.368		0.397
L2		0.8			0.031	
L4	0.6		1	0.023		0.039



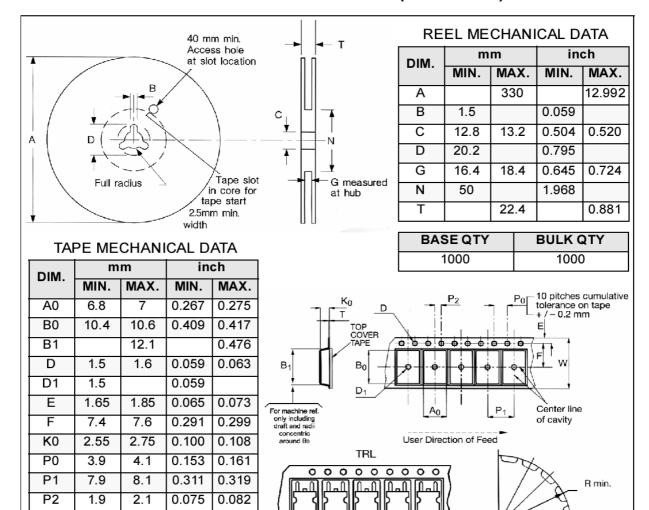
#### DPAK FOOTPRINT

# 6.7 1.8 3.0 1.6 2.3 1.6 All dimensions are in millimeters

#### **TUBE SHIPMENT (no suffix)\***



#### TAPE AND REEL SHIPMENT (suffix "T4")\*



FEED DIRECTION

R

W

40

15.7

16.3

1.574

0.618

0.641

4

Bending radius

<sup>\*</sup>on sales type

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